

MS 80 Manual Hot Melt Bead Applicator



The MS 80 works with granulate, chip or wafer formed hot melt adhesives, with no compressed air required.

The mechanical thermostat temperature control is set to the required level by a simple adjustment on the side of the applicator. You can adjust the temperature from 60°C to 200°C to suit the specific adhesive being used.

Simple top loading allows for quick recharging of the adhesive chamber, with either new or premelted product.

Various nozzles styles are available, a tool balancer, as well as pre-melting units to meet individual requirements and applications.

Technical Data for MS 80

NOTE: All specifications are adhesive dependent

Voltage	115V, 200W
No Air Required	
Temperature Control	Thermostat
Overheat protection	Thermal
Heat-up time, approx.	10 minutes
Tank capacity	80 grams
Extrusion rate, max. per minute	100 g/min
Electrical cord length	2 meters
Weight of handgun	750 grams

Adhesive Application Specialists